



Product Change Notification: MFOL-09UGKQ160

Date:

04-Aug-2025

Product Category:

8-Bit Microcontrollers, Analog Temperature Sensors, Power Management - System Supervisors/Voltage Detectors, Voltage References

Notification Subject:

CCB 7643 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP9700B, MCP130, MCP9700, MCP9700A, TC1047A, TC1047, MCP102, MCP9701, MCP9701A, TCM808, MCP1525, MCP1541 device families available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

Affected CPNs:

[MFOL-09UGKQ160_Affected_CPN_08042025.pdf](#)

[MFOL-09UGKQ160_Affected_CPN_08042025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP9700B, MCP130, MCP9700, MCP9700A, TC1047A, TC1047, MCP102, MCP9701, MCP9701A, TCM808, MCP1525, MCP1541 device families available in 3L SOT-23 (1.3mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)

Wire Material	Au	CuPdAu
Die Attach Material	8390A	8390A
Molding Compound Material	G600V	G600V
Lead-Frame Material	CDA194	CDA194

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 21 August 2025 (date code: 2534)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2025					>	August 2025				
Work Week	23	24	25	26	27		32	33	34	35	36
Initial PCN Issue Date		x									
Qual Report Availability							x				
Final PCN Issue Date							x				
Estimated Implementation Date									x		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 12, 2025: Issued initial notification.

August 04, 2025: Issued final notification. Attached qualification report. Provided estimated first ship date to be on August 21, 2025.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_MFOL-09UGKQ160_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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